

# 623-0303-H11 General Specifications

## ■ Mechanical

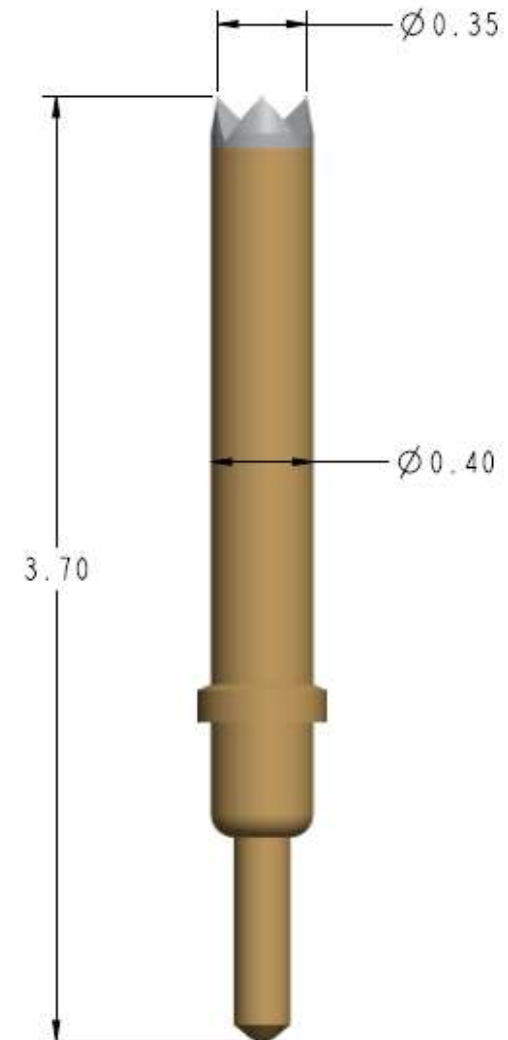
- Typical Application: BGA
- Minimum Device Pitch: 0.65 mm
- Force: 30 gf @ 0.60 mm Recommended Travel
- Operating Temperature Range: -55°C to 150°C
- Device Side Contact: 4-point Crown Tip
- PCB Side Contact : Conical Radius Tip

## ■ Electrical

- Bandwidth @ -1 dB: up to 20 GHz
  - Based on G-S-G Pattern
- Contact Resistance: < 50 mΩ average
- Current Carrying Capability: 3.0 A
  - Measured in free air

## ■ Plating

- Device Side Plunger: Homogenous alloy
- PCB Side Plunger : Gold plated
- Barrel: Gold plated
- Spring: Gold plated



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